



Integrated Device Technology, Inc.

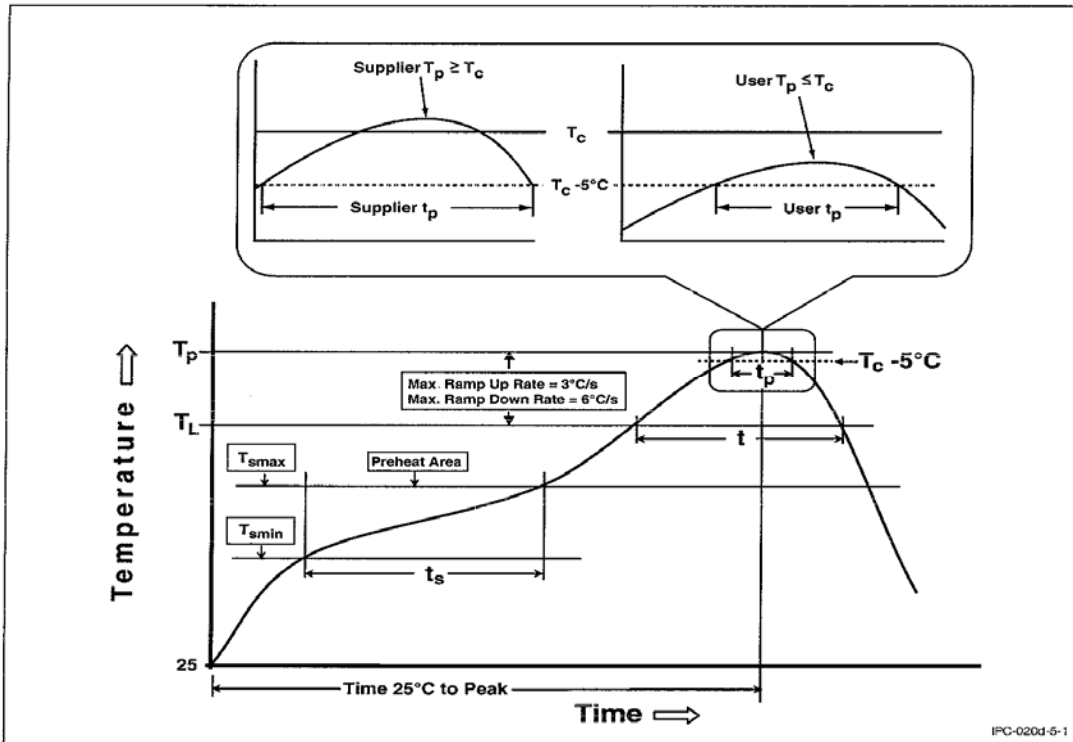
User Recommended Reflow Profile

Pb-Free Plastic Surface Mount Package

Profile Feature	Pb-Free Assembly (260 °C)
Preheat & Soak	
Temperature min (T_{smin})	150 °C
Temperature max (T_{smax})	200 °C
Time (T_{smin} to T_{smax}) (t_s)	60-120 seconds
Average ramp-up rate (T_{smax} to T_p)	3 °C/second max.
Liquidous temperature (T_L)	217 °C
Time at liquidous (t_L)	60-150 seconds
Peak package body (T_p)*	260°C
Time (t_p) ** within 5 °C of the specified classification temperature (T_c)	30** seconds
Average ramp-down rate (T_p to T_{smax})	6 °C/second max.
Time 25 °C to peak temperature	8 minutes max.

* Tolerance for peak profile temperature (T_p) is defined as a supplier minimum and a user maximum.

** Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.



Recommended Reflow Profile